

SERIAL	ITEM	TECHNICAL DATA
1	Board Type	Rigid Board, RF
2	Material	FR4 -TG 155 °C (NY2150), ROGERS (RO4003C)
3	Layers	1-8 Layers Pcb Prototype (Don't Support Blind /Buried Vias)
4	Max Board Size	400mm *500mm
5	Board Thickness	0.50mm - 3.20mm
6	Min line Width	0.15 mm
7	Min Space Width	0.10 mm
8	Min Hole Size	0.3 mm
9	Min Annular Ring	0.15mm
10	Copper Thickness	35um - 70um
11	Solder Mask Color	Green, Black, White, Blue, Red, Yellow
12	Silkscreen (Legend) Color	White, Black, Yellow
13	Surface Finishing	HASL -Hot Air Solder Leveling ENIG - Electro less Nickel / Immersion Gold
14	Electrical Test	Yes
15	AOI (Automatic Optical Inspection) Test	Yes
16	Core Specification For Multilayer ◦ FR4 -TG 155 °C (NY2150) ◦ Copper Thickness = 18 um	0.25mm◦0.30mm◦0.36mm◦0.40mm◦0.50mm 0.60mm◦0.70mm◦0.80mm◦1.00mm◦1.20mm ◦ 1.60mm
17	Prepreg Specification For Multilayer FR4-TG155°C (NY2150)	106 RC72%-Thickness 50um (2.00±0.5mil) 1080RC63% -Thickness 70um (2.80±0.5mil) 2313 RC58% -Thickness 100um (4.05±0.5mil) 2116 RC57% -Thickness 130um (5.15±0.5mil) 7628 RC52%-Thickness 220um (8.90±0.8mil)